PROCESS FOR PRODUCING CHIP AND PRESSURE SENSITIVE ADHESIVE SHEET FOR SAID PROCESS

ABSTRACT

A process for producing a chip, comprising the steps of:

attaching an object to be diced on a pressure sensitive adhesive sheet comprising at least one layer of shrinkable film and a pressure sensitive adhesive layer;

dicing the object into chips, and

shrinking the shrinkable film to thereby reduce an area in which the chips are in contact with the pressure sensitive adhesive. In this process, chips of small thickness and large area can easily be picked up without the need to use a thrust needle in the chip pickup step.

Figure 1